

Title (en)

PROCESS FOR MAPPING METAL CONTAMINANT CONCENTRATION ON A SILICON WAFER SURFACE

Title (de)

CHARAKTERISIERUNG DER METALLVERUNREINIGUNGSKONZENTRATION EINER SILIZIUMSCHEIBENOBERFLÄCHE

Title (fr)

PROCEDE DE CARTOGRAPHIE DE LA CONCENTRATION EN CONTAMINANTS METALLIQUES SUR LA SURFACE D'UNE PLAQUETTE DE SILICIUM

Publication

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Application

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Priority

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- US 9916109 W 19990716

Abstract (en)

[origin: WO0004579A1] A process is provided for preparing a reference wafer having a surface which is substantially uniformly contaminated with one or more metals of interest and which is suitable for use in the calibration of a total reflection fluorescent X-ray apparatus. The process comprises immersing a virgin wafer in a treatment solution obtained by mixing an aqueous stock solution containing a water-soluble salt of a metallic contaminant of interest with an organic solvent, and then drying thus immersed wafer.

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H01L 21/66

IPC 8 full level

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